

Title (en)

Copper alloy having excellent corrosion cracking resistance and dezincing resistance, and method for producing same

Title (de)

Kupferlegierung, die exzellente Korrosionsbeständigkeit und Entzinkungsbeständigkeit aufweist, und eine Methode zu deren Herstellung

Title (fr)

Alliage de cuivre, qui a une excellente résistance à la corrosion et au dézincage, et procédure de fabrication

Publication

**EP 1508625 A1 20050223 (EN)**

Application

**EP 03018581 A 20030818**

Priority

EP 03018581 A 20030818

Abstract (en)

A copper alloy having an excellent corrosion cracking resistance and an excellent dezincing resistance consists of: 58 to 66 wt% of copper (Cu); 0.1 to 0.8 wt% of Sn; 0.01 to 0.5 wt% of Si; at least one of 0.3 to 3.5 wt% of lead (Pb) , 0.3 to 3.0 wt% of bismuth (Bi) , 0.02 to 0.15 wt% of phosphorus (P), 0.02 to 3.0 wt% of nickel (Ni) and 0.02 to 0.6 wt% of iron (Fe) if necessary; and the balance being zinc (Zn) and unavoidable impurities, wherein the proportion of an alpha phase is 80 vol% or more. The apparent content of zinc (Zn) in the copper alloy is in the range of from 34 to 39 wt%.

IPC 1-7

**C22C 9/04**; **C22F 1/08**

IPC 8 full level

**C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP)

**C22C 9/04** (2013.01); **C22F 1/08** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

**EP 1508625 A1 20050223**; **EP 1508625 B1 20070214**; AT E353981 T1 20070315; DE 60311803 D1 20070329; DE 60311803 T2 20071031

DOCDB simple family (application)

**EP 03018581 A 20030818**; AT 03018581 T 20030818; DE 60311803 T 20030818